



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-12-14
Contact Name *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EU6S*UF96JC1	A	Z8GA	2015-12-14
Amount	UoM	Unit type	ST ECOPACK Grade	
54.50	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
D50	5.0X4.4X0.9	16	gull wing	
Comment	Package: TSSOP 16 BODY 4.4 PITCH 0.65; MD valid for ST26C31BTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EU65*UF96IC1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	1.788	mg	supplier	die	Silicon (Si)	7440-21-3		1.726	mg	965324	31670
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	7830	257
Silicon Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	2796	92
Silicon Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	13423	440
Silicon Die				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.019	mg	10626	349
Leadframe	Copper and its alloy	19.647	mg	Supplier	Alloy	Copper(CU)	7440-50-8		18.555	mg	944419	340459
Leadframe				Supplier	Alloy	Silicon	7440-21-3		0.136	mg	6922	2495
Leadframe				Supplier	Alloy	Mg	7439-95-4		0.031	mg	1578	569
Leadframe				Supplier	Alloy	Nickel	7440-02-0		0.619	mg	31506	11358
Leadframe				Supplier	Alloy	Silver(Ag)	7440-22-4		0.306	mg	15575	5615
Die Attach	Other Organic Material	0.818	mg	Supplier	Epoxy	Silver(Ag)	7440-22-4		0.637	mg	778729	11688
Die Attach				Supplier	Epoxy	Acrylate resins	Proprietary		0.147	mg	179707	2697
Die Attach				Supplier	Epoxy	Heterocyclic organic compound	Proprietary		0.017	mg	20782	312
Die Attach				Supplier	Epoxy	Treated silica	Proprietary		0.017	mg	20782	312
Bonding wire	Other Inorganic Material	0.240	mg	Supplier	Bonding wire	Gold(Au)	7440-57-5		0.240	mg	1000000	4404
Encapsulation	Other Organic Material	30.076	mg	Supplier	Molding compound	Silica	60676-86-0		27.334	mg	908831	501541
Encapsulation				Supplier	Molding compound	Epoxy resin-1	Proprietary		0.914	mg	30390	16771
Encapsulation				Supplier	Molding compound	Epoxy resin-2	Proprietary		0.549	mg	18254	10073
Encapsulation				Supplier	Molding compound	Phenol Resin	Proprietary		1.218	mg	40497	22349
Encapsulation				Supplier	Molding compound	Carbon Black	1333-86-4		0.061	mg	2028	1119
Finishing	Other Inorganic Material	1.931	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		1.931	mg	1000000	35431